

ABSTRACT OF THE INVENTION

Optoelectronic packages comprise both an optical array and base chip. The array and base chip are aligned and coupled using a combination of V-grooves, wick stops, and alignment spheres (e.g., precision ball bearings). The array and base chip are passively aligned by disposing an optical fiber having an angled endface onto V-grooves in both the array and base chip. The base chip typically comprises an optical surface device, such as a vertical cavity, surface emitting laser or photodetector.